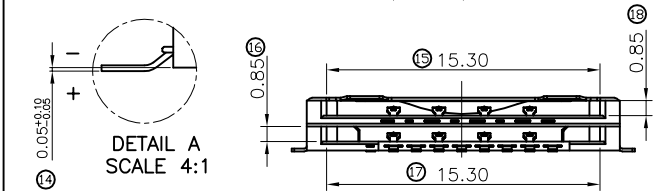
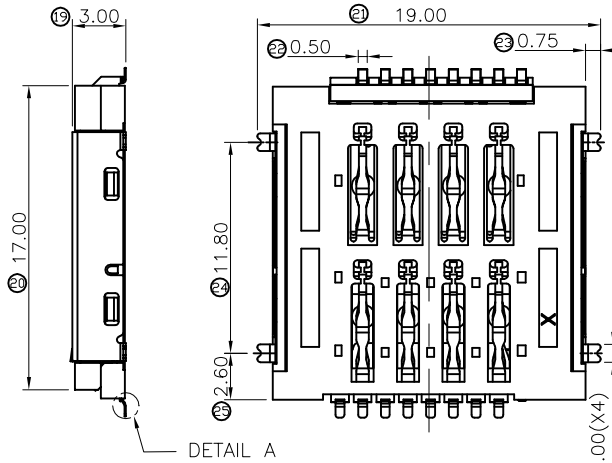
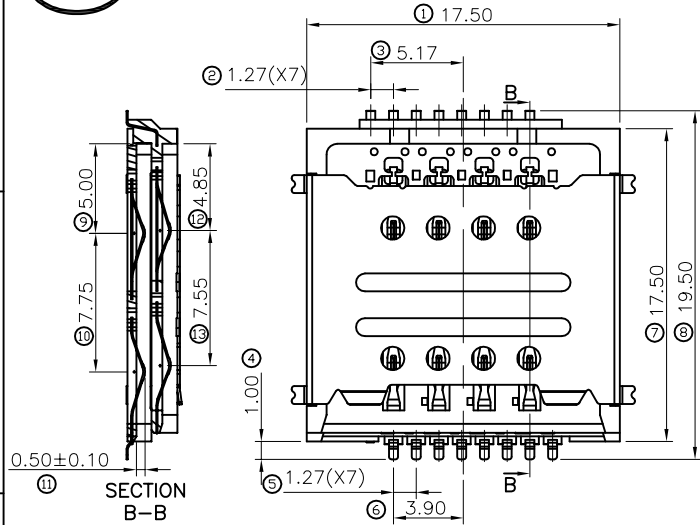
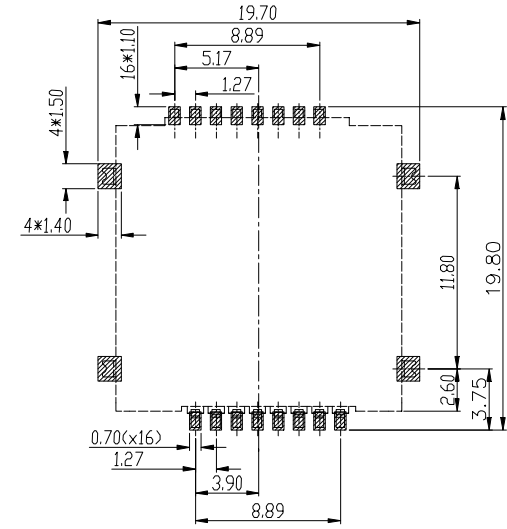


HF

REV	DATE	ECN NO.	MODIFICATION	APPROVER
A0	2023/02/08		NEW	

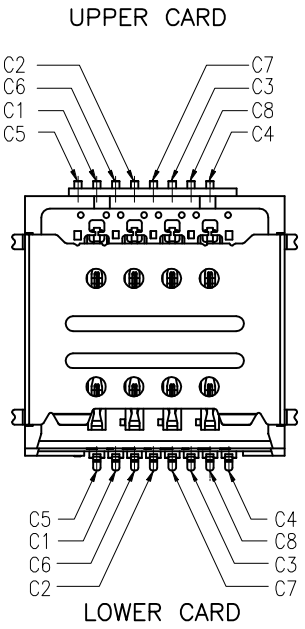


- NOTES
- MATERIAL:
 - Housing: HI-TEMP Plastic, UL94V-0, Black.
 - Terminal: Copper alloy,
 - FINISH:
 - Terminal: 3u" Au plating on contact area, 1u" gold plating on solder area over nickel
 - Shell Au plated on the solder tails underplated over nickel.
 - Electrical performance:
 - Contact Resistance: 50mΩ Max
 - Dielectric Withstanding voltage: 350V AC rms for 1minute
 - Insulation resistance: 1000MΩ Min
 - Mechanical performance.
 - Durability: 5000 cycles
 - Normal force: 20gf/PIN Min:
 - HF and REACH Compliance

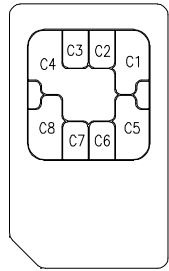


SOLDER PAD

RECOMMENDED PCB LAYOUT TOLERANCE: ±0.05



C1	C1:VCC
C2	C2:RST
C3	C3:CLK
C4	C4:RESERVED
C5	C5:GND
C6	C6:VPP
C7	C7:I/O
C8	C8:RESERVED



SIM CARD CIRCUIT

GENERAL TOLERANCE	UNITS mm	NAME: SIM CARD	ATOM® 深圳市爱特姆科技有限公司 SHENZHEN ATOM TECHNOLOGY CO., LTD.		
SELECT		PART NO:	TITLE:		
DN.	TOL 1 2 3	S112C-08200	16PIN 3.0H DOUBLE SIM CONN 防泼PIN		
X.XXX	±0.10 ±0.05 ±0.15	APPD:	DWG NO. ATOM-A07652		
X.XX	±0.15 ±0.13 ±0.25	CHKD:	SCALE SHEET REV		
X.X	±0.20 ±0.25 ±0.5	DR:	1:1 1/1 AO		
X.	±0.30 ±0.38 ±1.00				
ANGLE	±2°				